



#### P-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

BV <sub>DSS</sub>	Rds(on) Max	I <sub>D</sub> Max T <sub>A</sub> = +25°C
	29mΩ @ V <sub>GS</sub> = -4.5V	-6.9A
-20V	39mΩ @ V <sub>GS</sub> = -2.5V	-5.9A

## **Features and Benefits**

- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Low Gate Threshold Voltage
- Low On-Resistance
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

 $\underline{\text{https://www.diodes.com/products/automotive/automotive-products/.}}$ 

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

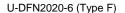
## **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

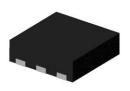
- Battery Management Application
- Power Management Functions
- DC-DC Converters

#### **Mechanical Data**

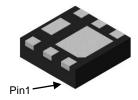
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 4
- Weight: 0.0065 grams (Approximate)



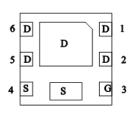




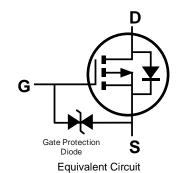
Top View



Bottom View



Pin Out Bottom View



### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMP2035UFDF-7	U-DFN2020-6 (Type F)	3,000/Tape & Reel
DMP2035UFDF-13	U-DFN2020-6 (Type F)	10.000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



## **Marking Information**

Site 1



P8 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Kev

Year	2016		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	D		Н		J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	Mav	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



P8 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Kev

Date Code Key												
Year	2016		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	6		0	1	2	3	4	5	6	7	8	9
147										_	_	
Week	1-26			27-52				53				
Code		A-Z			A-Z a-z				Z			
Internal Code	Sun		Mon		Tue	W	od	Thu		Fri		Sat
	Juli		IVIOII		Tue			IIIu		1 11		Jai
Code	Т		U		V	V	V	X		Υ		Z



## **Maximum Ratings** (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	$V_{DSS}$	-20	V		
Gate-Source Voltage	Vgss	±8	V		
Continuous Drain Current (Note C) Ves 45V	Steady State	$T_A = +25$ °C $T_A = +70$ °C	I <sub>D</sub>	-6.9 -5.5	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = -4.5V	t<10s	$T_A = +25$ °C $T_A = +70$ °C	lo	-8.1 -6.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	)		I <sub>DM</sub>	-40	Α
Continuous Source-Drain Diode Current (Note 6)	Is	-2.5	Α		
Avalanche Current (Note 7) L = 0.1mH	I <sub>AS</sub>	-21	Α		
Avalanche Energy (Note 7) L = 0.1mH			Eas	23	mJ

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25$ °C	D-	0.66	W
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70°C	PD	0.42	VV
Thermal Begistance, Junction to Ambient (Note 5)	Steady State	Rела	180	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t<10s	Көја	135	C/VV
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	D-	2.03	W
Total Power Dissipation (Note 6)	$T_A = +70$ °C	P <sub>D</sub>	1.31	VV
Thermal Begistance, Junction to Ambient (Note 6)	Steady State	Rела	63	
Thermal Resistance, Junction to Ambient (Note 6)	t<10s	Көја	43	°C/W
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	17.5	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	ů

## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BVDSS	-20		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	-1	μΑ	$V_{DS} = -16V, V_{GS} = 0V$	
Gate-Source Leakage	lgss	_	_	±10	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	-0.4	I	-1.0	V	$V_{DS} = V_{GS}$ , $I_D = -250\mu A$	
			20	29		$V_{GS} = -4.5V$ , $I_{D} = -6.4A$	
Static Drain-Source On-Resistance	RDS(ON)	_	24	39	mO.	$V_{GS} = -2.5V$ , $I_{D} = -4.8A$	
Static Drain-Source Off-Resistance			31	60	mΩ	$V_{GS} = -1.8V, I_{D} = -2.5A$	
			40	120		$V_{GS} = -1.5V$ , $I_{D} = -1.5A$	
Diode Forward Voltage	VsD	_	-0.7	-1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = -1.0A	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	1,808	_			
Output Capacitance	Coss	_	155	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	117	_		1 = 1.000112	
Gate Resistance	Rg	_	32	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = -4.5V)	$Q_G$	_	20.5	_		10)/ )/ 15)/	
Gate-Source Charge	Qgs	_	2.8	_	nC	$V_{DS} = -10V$ , $V_{GS} = -4.5V$ ,	
Gate-Drain Charge	Q <sub>GD</sub>	_	4.1	_		$I_D = -4.0A$	
Turn-On Delay Time	td(on)	_	9.1	_			
Turn-On Rise Time	t <sub>R</sub>	_	12.3	_	20	$V_{DS} = -10V$ , $V_{GS} = -4.5V$ ,	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	120	_	ns	$R_G = 6\Omega$ , $I_D = -1.0A$	
Turn-Off Fall Time	t <sub>F</sub>	_	54	_			
Reverse Recovery Time	trr	_	23.1	_	ns	I <sub>F</sub> = -1.0A, di/dt = 100A/µs	
Reverse Recovery Charge	Q <sub>RR</sub>		8.3		nC	$I_F = -1.0A$ , $di/dt = 100A/\mu s$	

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

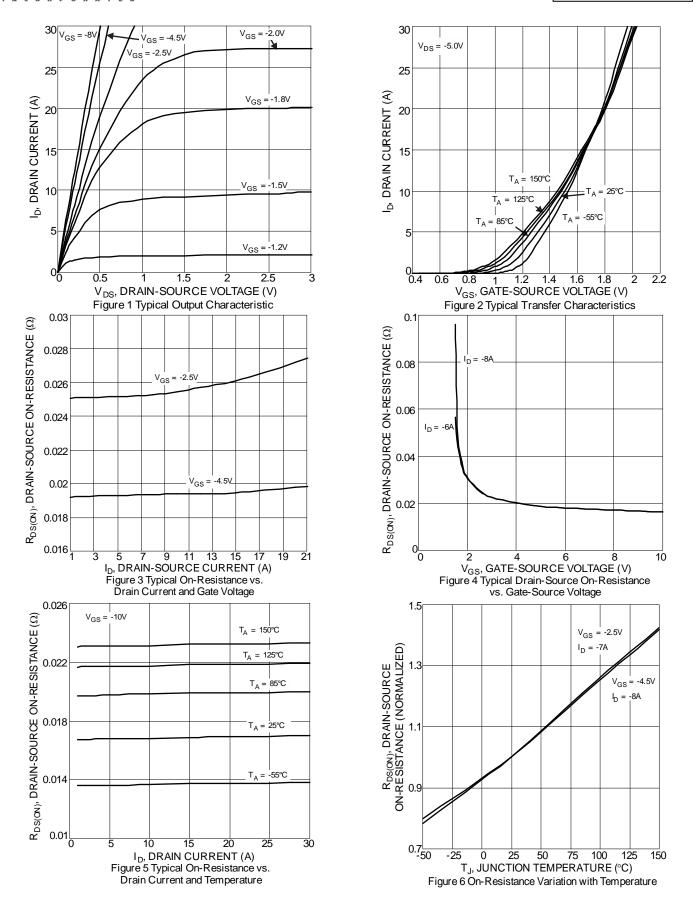
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.

7.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J$  = +25°C.

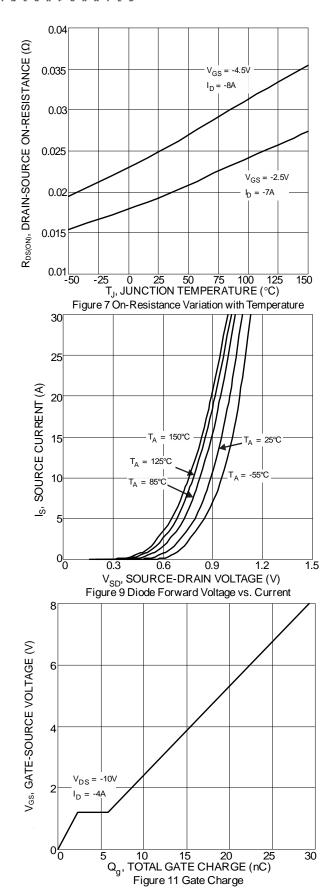
8. Short duration pulse test used to minimize self-heating effect.

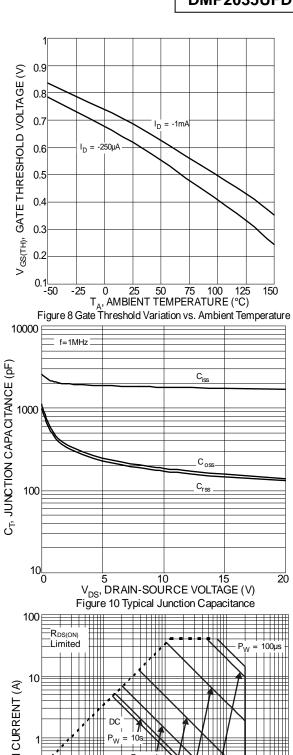
9. Guaranteed by design. Not subject to product testing.



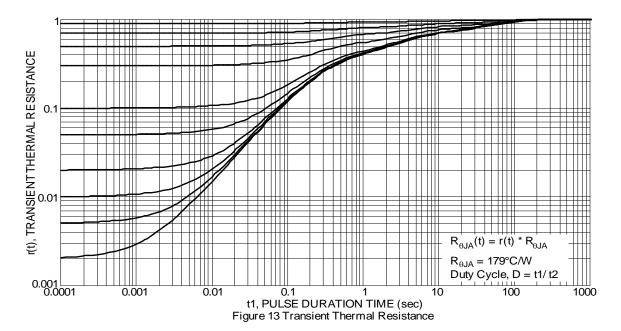










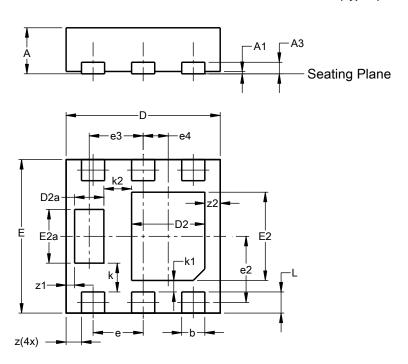




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### U-DFN2020-6 (Type F)

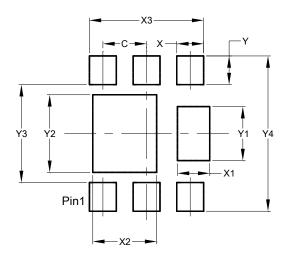


U-DFN2020-6						
	(Тур	oe F)				
Dim	Min	Max	Тур			
Α	0.57	0.63	0.60			
A1	0.00	0.05	0.03			
A3	-	-	0.15			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.85	1.05	0.95			
D2a	0.33	0.33 0.43 (				
Е	1.95	2.05	2.00			
E2	1.05	1.25	1.15			
E2a	0.65	0.75	0.70			
е		0.65 BS	C			
e2		).863 BS	SC			
e3		0.70 BS				
e4		).325 BS				
k		0.37 BS	С			
k1		0.15 BS				
k2		0.36 BS	С			
L	0.225	0.325	0.275			
Z		0.20 BS				
<b>z</b> 1		).110 BS				
z2		0.20 BS	_			
All C	Dimens	ions in	mm			

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### U-DFN2020-6 (Type F)



Dimensions	Value
	(in mm)
С	0.650
Х	0.400
X1	0.480
X2	0.950
Х3	1.700
Υ	0.425
Y1	0.800
Y2	1.150
Y3	1.450
Y4	2.300



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